

REMARKS

I. Status of the Application

In the March 5, 2003 Notice of Non-Compliant Amendment, the Examiner has requested a clean version of claim 17. In this response, Applicant has provided a clean revision of claim 17.

II. Conclusion

It is respectfully submitted that all claims are in condition for allowance. Accordingly, prompt and favorable examination is earnestly solicited.

Respectfully Submitted,



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APPENDIX

Pursuant to 37 C.F.R. Section 1.121(c)(1)(ii), below are the changes to claim 17.

17. (amended) A method of fabricating a semiconductor wafer, comprising:

(a) subjecting said semiconductor wafer to a pressure; and

(b) measuring said pressure said semiconductor is subjected to with a pressure measurement device supported on said semiconductor wafer, said pressure measurement device including (i) a capacitor, (ii) capacitance measurement circuitry electrically coupled to said capacitor, and (iii) capacitance to pressure conversion circuitry electrically coupled to said capacitance measurement icruity, and further including converting a capacitance of said capacitor to a pressure with said capacitance to pressure conversion circuitry.